ABSTRACT

An adhesive film for a semiconductor is disclosed. The adhesive film for a semiconductor contains an epoxy resin, a phenol resin, and a modified elastomer. The modified elastomer is a reaction product of an elastomer having an epoxy group and a phenol resin. The adhesive film for a semiconductor may be used for bonding a semiconductor chip to a substrate while embedding another semiconductor chip. The adhesive film for a semiconductor may be used for bonding a semiconductor chip to another semiconductor chip while embedding part or all of a wire connected to the other semiconductor chip.

FIG. 1